



High Bit Rate High Density

FACILITIES IN NORTH AMERICA CAMBRIDGE (MD) & SAN DIEGO (CA) AND IN FRANCE (BOLLÈNE)

TECHNOLOGIES

- HTCC Ceramic
- Assembly Glass to Metal & Ceramic to Metal
- Plating
- Power Material & Power Management

SPECIAL MATERIALS AND ALLOYS

Kovar, Copper-Tungsten, Molybdenum, Copper-Molybdenum, Beryllium Oxide, Aluminum, Titanium, Aluminum Graphite, S-CMC...

PLATING

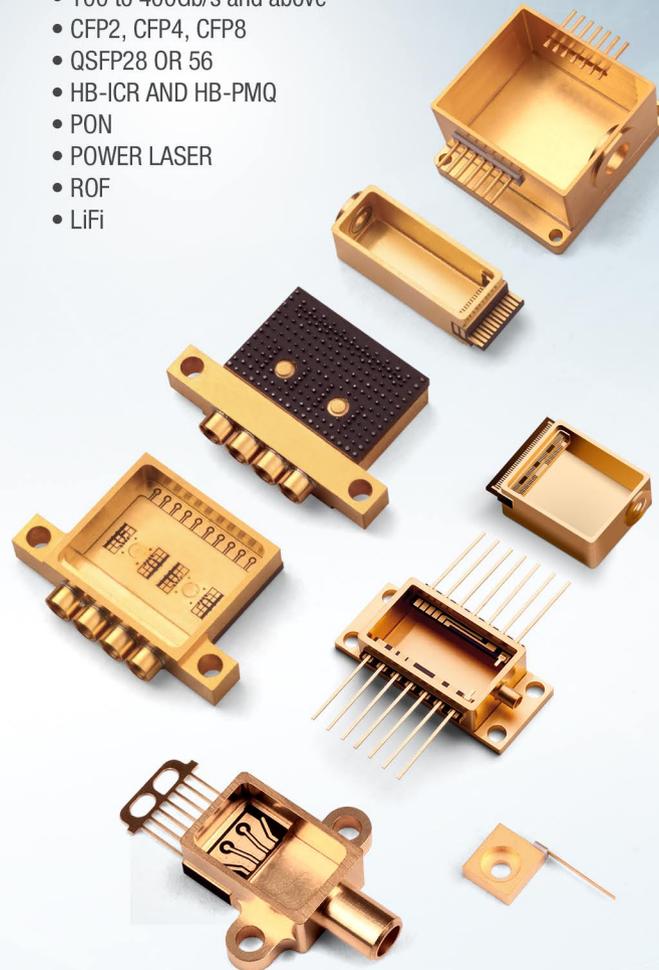
- Gold, Nickel, Silver and Copper
- Electrolytic
- Electroless



High Power

OPTICAL PACKAGES FOR

- 100 to 400Gb/s and above
- CFP2, CFP4, CFP8
- QSFP28 OR 56
- HB-ICR AND HB-PMQ
- PON
- POWER LASER
- ROF
- LiFi



High Reliability

PRODUCT FAMILIES

- TOSA & ROSA
- ICR & μ -ICR
- IC-TROSA
- DM & CW Laser
- PUMPS
- WSS & WM
- Filters
- POWER Laser

